

## Abstract

385

Electronic Module, in Particular a Multichip Module,  
Comprising a Multilayer Wiring and Method of Making the  
Same

390

The component side of the multilayer wiring (2) adheres  
with its component-free portions to the hermetic case  
(4), and the bottom side of the multilayer wiring (2)  
having a height of less than approx. 100  $\mu\text{m}$ , directly,  
395 i.e. without additional wiring substrate (1), consti-  
tutes the bottom side of the module.

Figure 1